

FEATURES

High Speed Switching
High Blocking Voltage with Low $R_{DS(on)}$
Easy to Parallel
Simple to Drive
RoHS Compliant

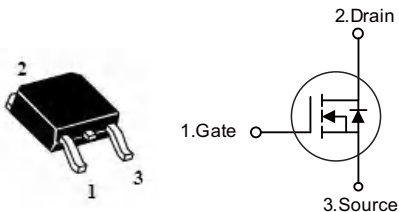
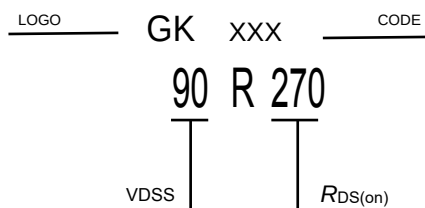
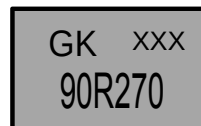
APPLICATION

Increased Power Density
Faster Operating Frequency
Reduction of Heat Sink Requirements
Higher Efficiency
Reduced EMI

APPLICATION

Power Factor Correction Modules
Switch Mode Power Supplies
DC-AC Inverters
High Voltage DC/DC Converters

V_{DS} 900 V
 I_D 13 A
 $R_{DS(ON)}$ 270 m Ω



ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameter	Test conditions	Value	Unit
V_{DS}	Drain-Source Voltage		900	V
I_D	Continuous Drain Current	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	13 9.2	A
I_{DM}	Peak Drain Current	Pulse width t_p limited by T_{jmax}	24	A
V_{GSmax}	Gate-Source Voltage		-8/+22	V
V_{GSop}	Recommend Gate-Source Voltage		-4/+18	V
P_{tot}	Power Dissipation	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	57 28.5	W
T_j	Operating Junction Temperature		-40~175	$^\circ\text{C}$
T_{stg}	Storage Temperature		-40~175	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$, unless otherwise specified)

Static Characteristics

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D=100\mu\text{A}$, $V_{GS}=0\text{V}$	900			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=900\text{V}$, $V_{GS}=0\text{V}$		1		μA
I_{GSS}	Gate-Source Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=18\text{V}$			250	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=1.33\text{mA}$ $T_j=25^{\circ}\text{C}$ $T_j=175^{\circ}\text{C}$	2	3.1 2.2	4	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=15\text{V}$, $I_D=4.5\text{A}$ $T_j=25^{\circ}\text{C}$ $T_j=175^{\circ}\text{C}$		370 340	500	$\text{m}\Omega$
		$V_{GS}=18\text{V}$, $I_D=4.5\text{A}$ $T_j=25^{\circ}\text{C}$ $T=175^{\circ}\text{C}$		270 298	357	

Dynamic Characteristics

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
C_{iss}	Input Capacitance	$V_{DS}=600\text{V}$, $f=1\text{MHz}$, $V_{GS}=0\text{V}$		203		pF
C_{oss}	Output Capacitance			26		pF
C_{rss}	Reverse Transfer Capacitance			3.5		pF
$R_{G(int)}$	Internal Gate Resistance	$f=1\text{MHz}$		3.6		Ω
Q_g	Total Gate Charge	$V_{DS}=400\text{V}$, $I_D=4.5\text{A}$, $V_{GS}=-4/18\text{V}$		11.2		nC
Q_{gs}	Gate to Source Charge			2		nC
Q_{gd}	Gate to Drain Charge			5.2		nC

Thermal Characteristics

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
$R_{th(j-c)}$	Thermal Resistance from Junction to Case		2.63		$^{\circ}\text{C/W}$

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$, unless otherwise specified)

Switching Characteristics

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=400\text{V}$, $I_D=4.5\text{A}$, $V_{GS}=-4\text{V}/18\text{V}$, $R_G=2.5\Omega$, $L=200\mu\text{H}$		3		ns
t_r	Rise Time			8		ns
$t_{d(off)}$	Turn-Off Delay Time			6		ns
t_f	Fall Time			11		ns
E_{on}	Turn-On Energy			21		μJ
E_{off}	Turn-Off Energy			5		μJ

Reverse Diode Characteristics

Symbol	Parameter	Test conditions	Value			Unit
			Min.	Typ.	Max.	
V_{SD}	Diode Forward Voltage	$V_{GS}=-4\text{V}$, $I_{SD}=2.5\text{A}$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$ $V_{GS}=-4\text{V}$, $I_{SD}=4.5\text{A}$ $T_j=25^\circ\text{C}$ $T_j=175^\circ\text{C}$		4.0 3.6 4.5 4.0		V
I_S	Continuous Diode Forward Current	$V_{GS}=-4\text{V}$ $T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$		13 6.5		A
t_{rr}	Reverse Recovery Time	$V_{GS}=-4\text{V}$, $I_{SD}=4.5\text{A}$, $V_R=400\text{V}$, $di/dt=1000\text{A}/\mu\text{s}$		10		ns
Q_{rr}	Reverse Recovery Charge			56		nC
I_{rrm}	Peak Reverse Recovery Current			4		A

RATING AND CHARACTERISTIC CURVES

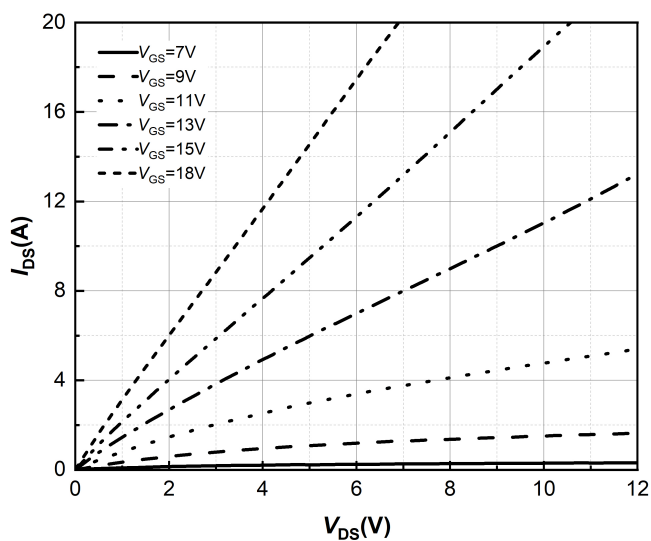


Figure 1. Output Characteristics
 $T_j = -40^\circ\text{C}$

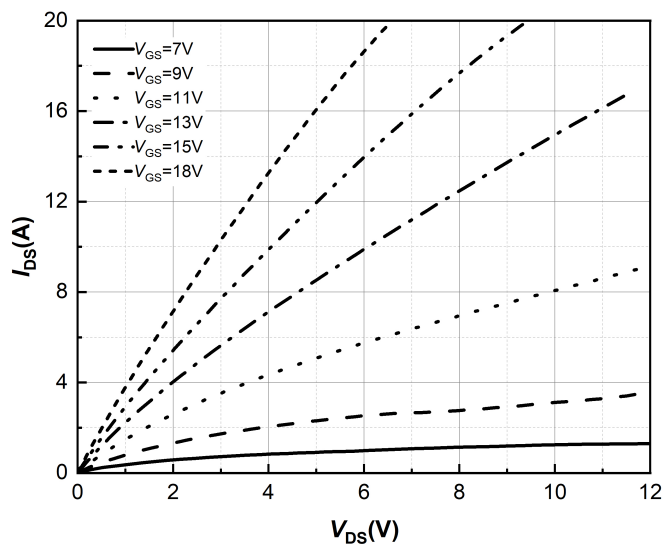


Figure 2 Output Characteristics

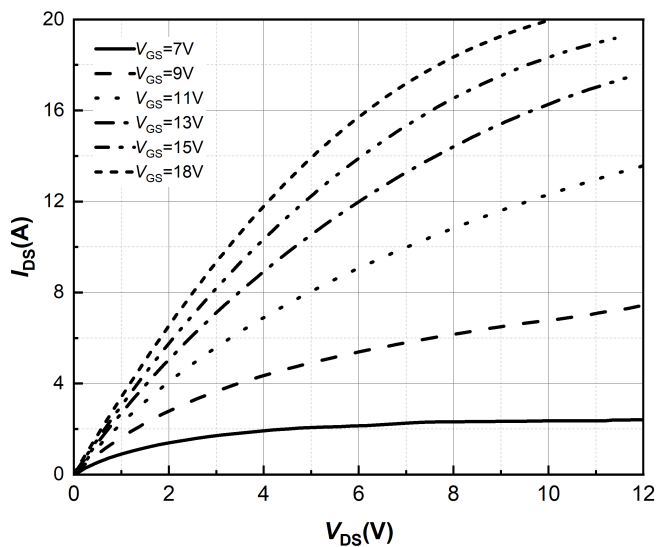


Figure 3. Output Characteristics
 $T_j = 175^\circ\text{C}$

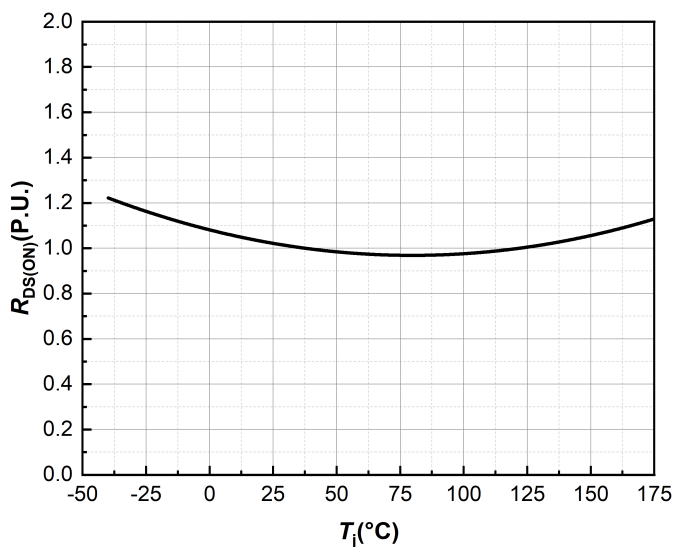


Figure 4. Normalized On-Resistance vs.
Temperature

RATING AND CHARACTERISTIC CURVES

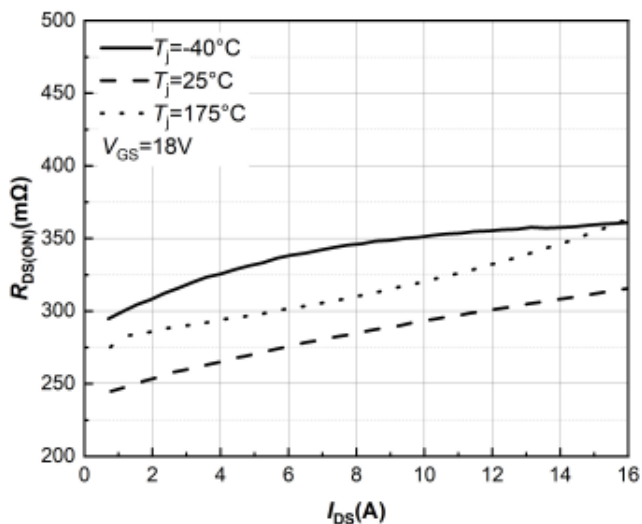


Figure 5. On-Resistance vs. Drain Current
For Various Temperatures

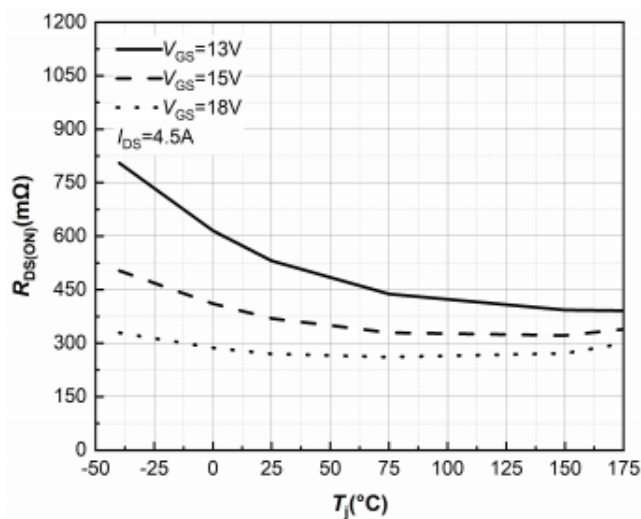


Figure 6. On-Resistance vs. Temperature
For Various Gate Voltage

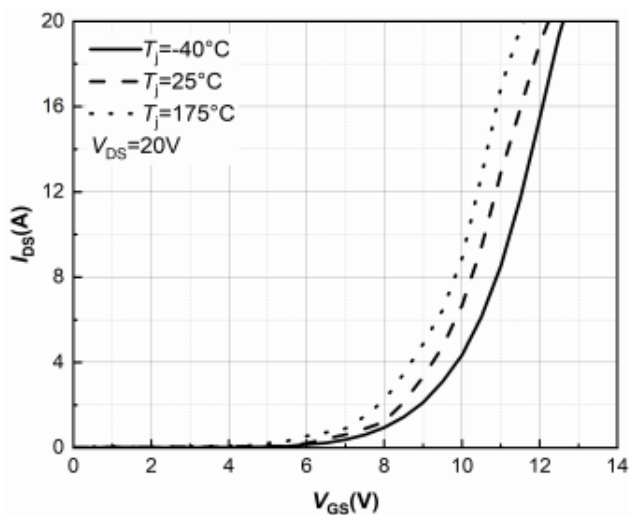


Figure 7. Transfer Characteristic for
Various Junction Temperatures

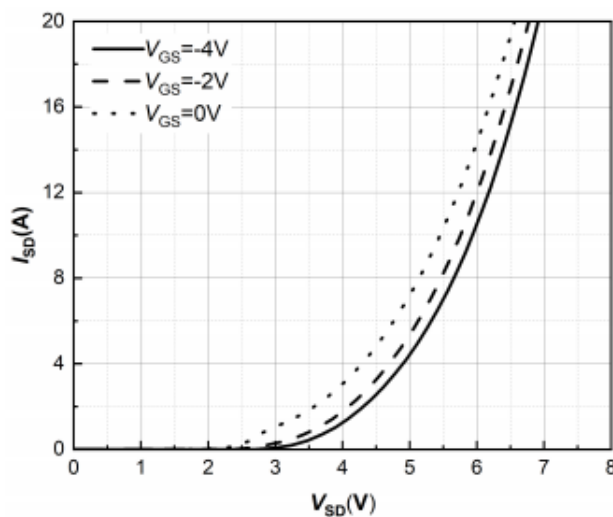


Figure 8. Body Diode Characteristic
 $T_J = -40^{\circ}\text{C}$

RATING AND CHARACTERISTIC CURVES

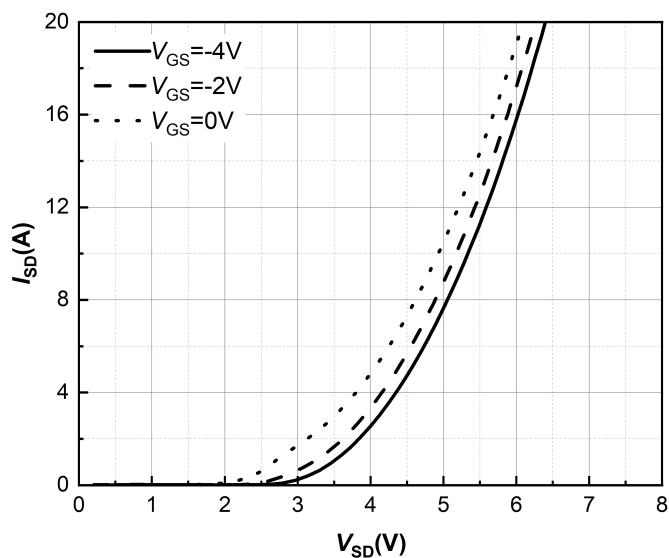


Figure 9. **Body Diode Characteristic**
 $T_j=25^{\circ}\text{C}$

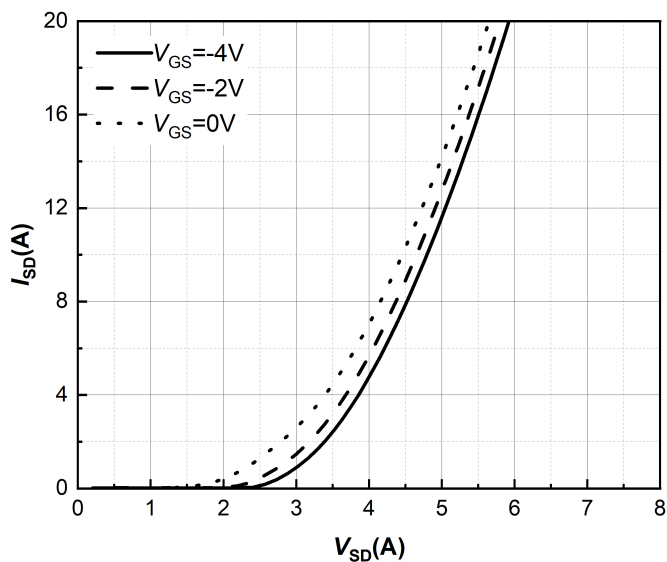


Figure 10. **Body Diode Characteristic**
 $T_j=175^{\circ}\text{C}$

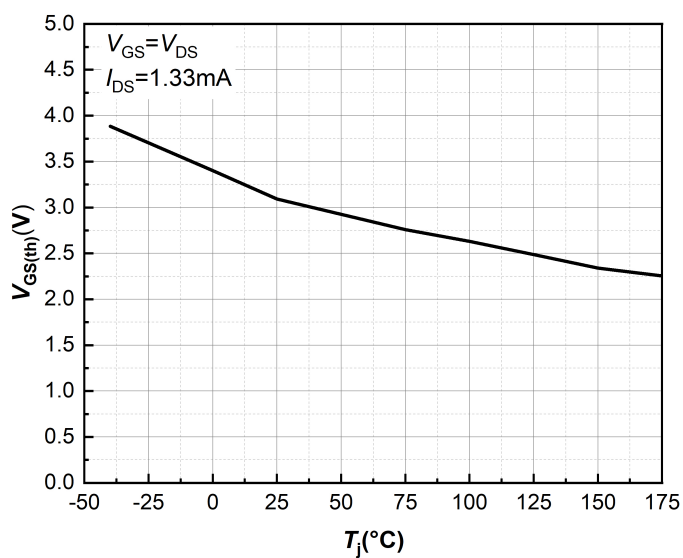


Figure 11. **Threshold Voltage vs. Temperature**

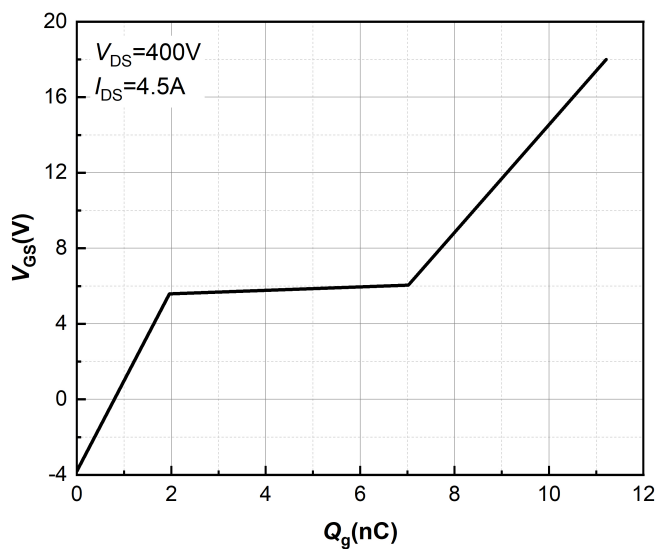


Figure 12. **Gate Charge Characteristics**

RATING AND CHARACTERISTIC CURVES

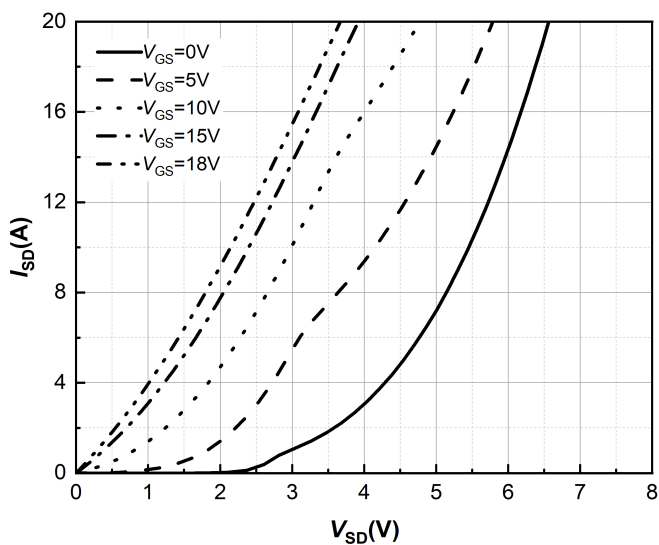


Figure 13. 3rd Quadrant Characteristic
 $T_j = -40^{\circ}\text{C}$

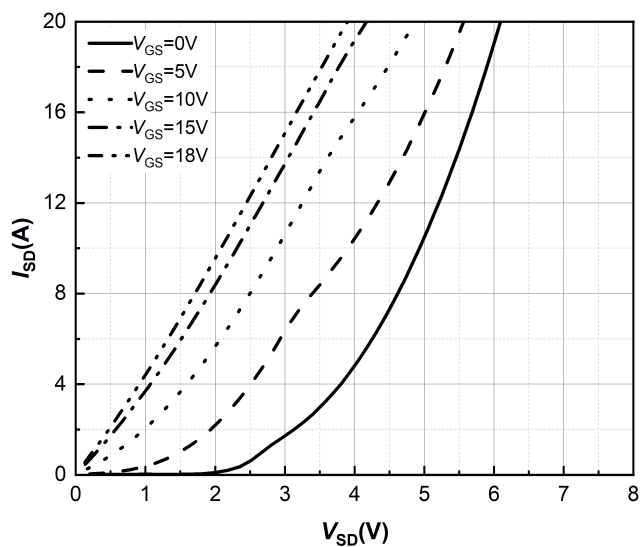


Figure 14. 3rd Quadrant Characteristic
 $T_j = 25^{\circ}\text{C}$

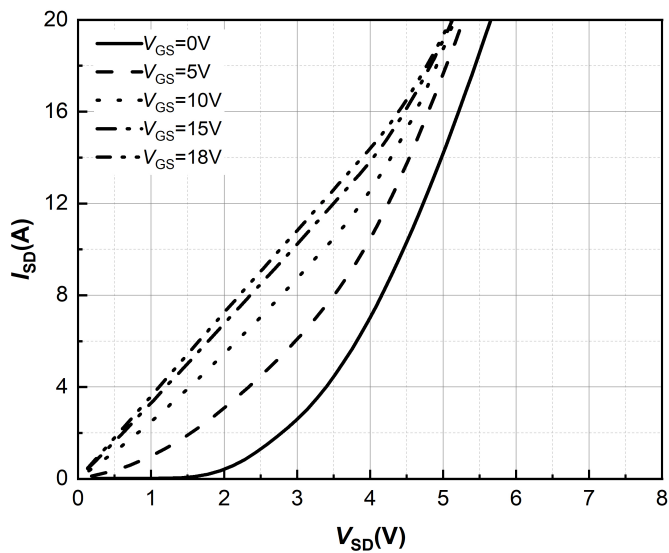


Figure 15. 3rd Quadrant Characteristic
 $T_j = 175^{\circ}\text{C}$

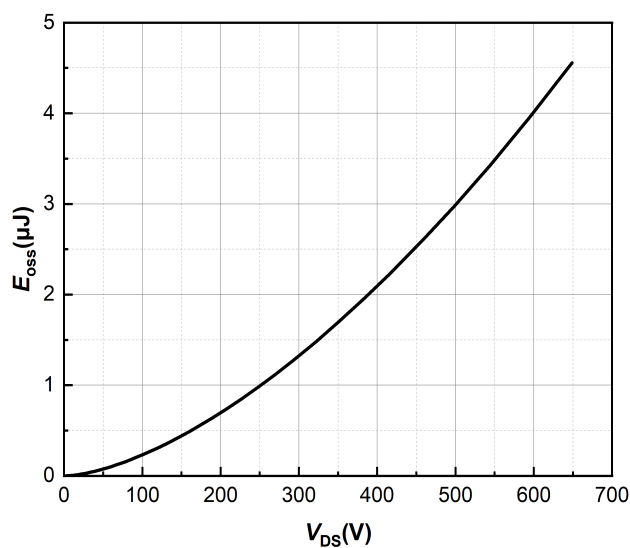


Figure 16. Output Capacitor Stored
Energy

RATING AND CHARACTERISTIC CURVES

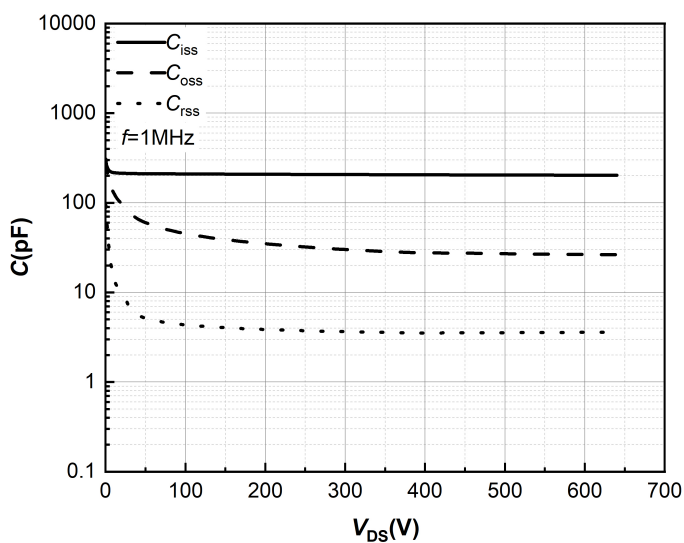


Figure 17. Capacitances vs. Drain-Source

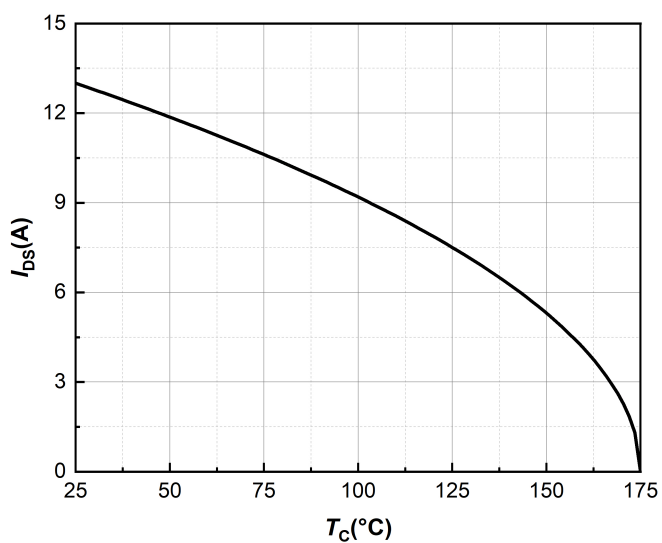


Figure 18. Continuous Drain Current Derating vs. Case Temperature

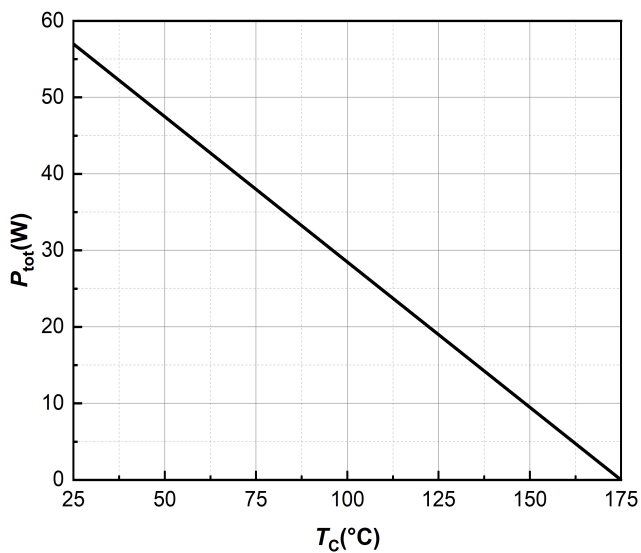


Figure 19. Maximum Power Dissipation Derating vs. Case Temperature

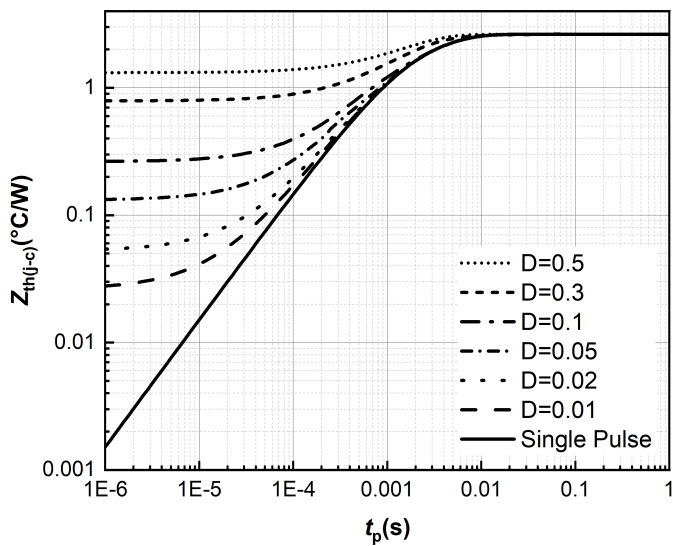


Figure 20. Transient Thermal Impedance

RATING AND CHARACTERISTIC CURVES

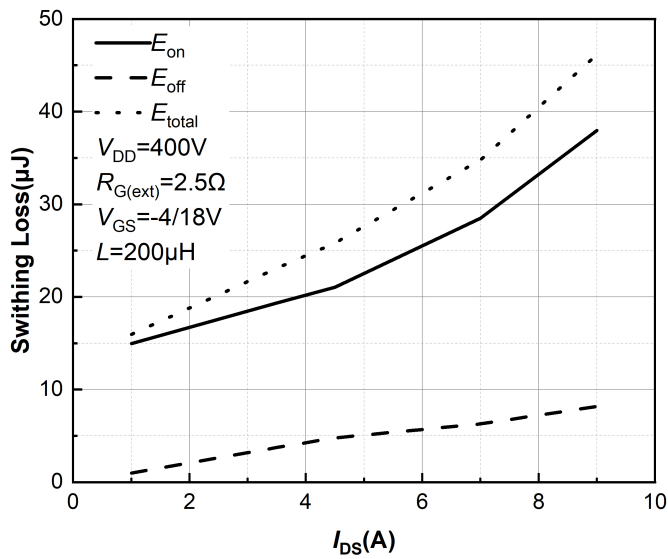


Figure 21. Clamped Inductive Switching Energy vs. Drain Current

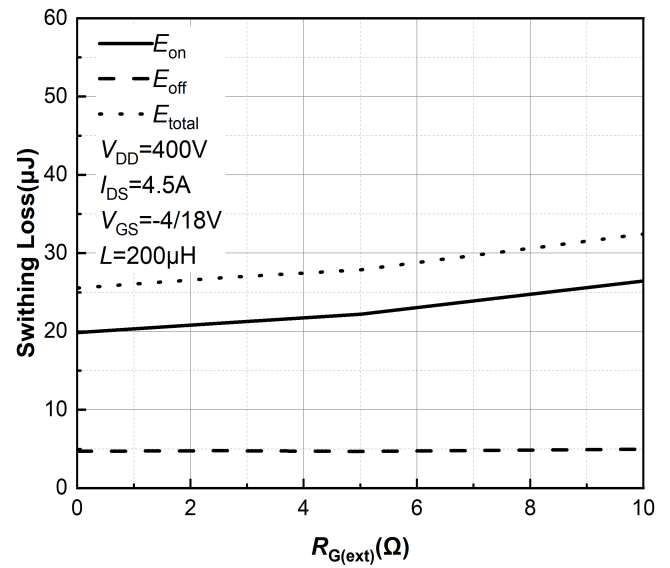


Figure 22. Clamped Inductive Switching Energy vs. R_G

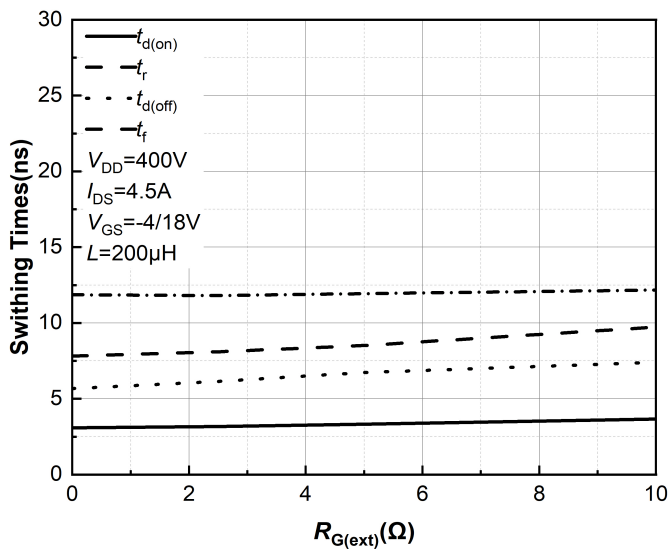


Figure 23. Switching Times vs. R_G

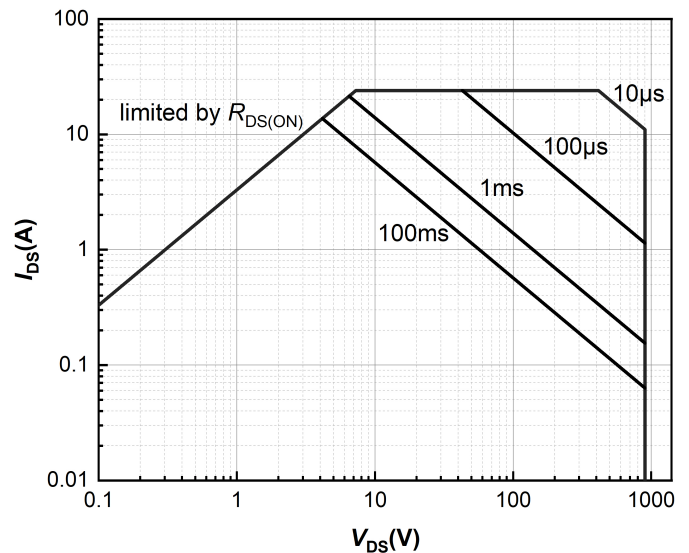
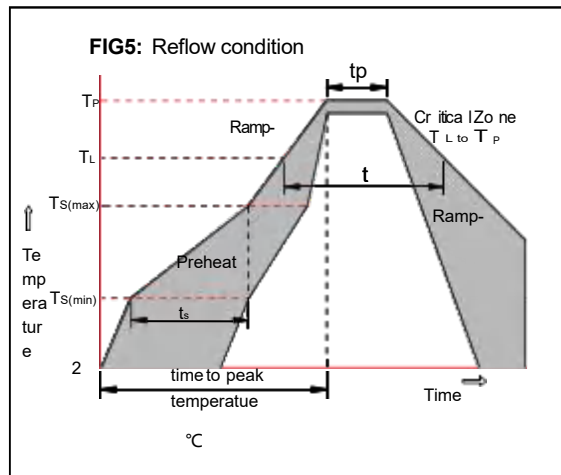


Figure 24. Safe Operating Area

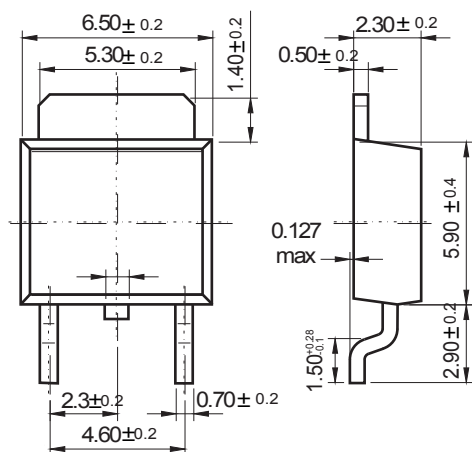
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max ($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C

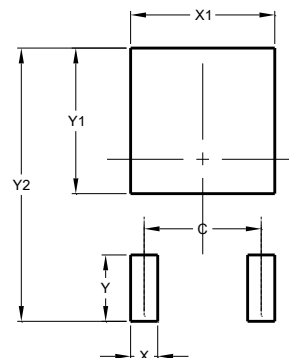


Package Dimensions & Suggested Pad Layout

TO-252

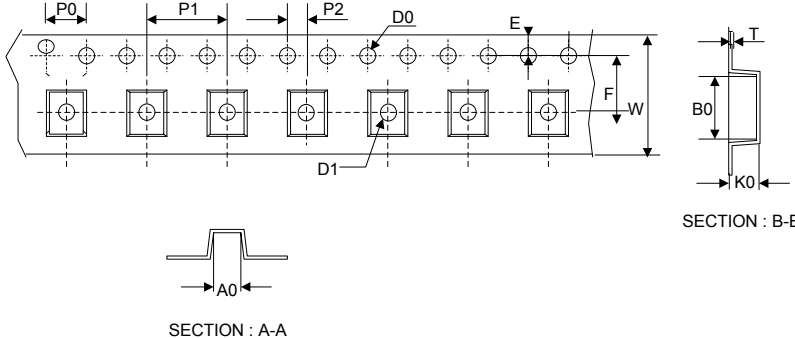
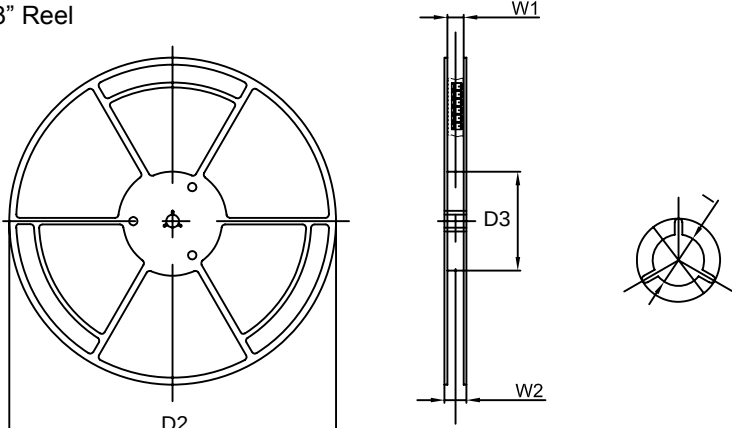


Dimensions in inches and (millimeters)



Dimensions	Value (in mm)
C	4.55
X	1.50
X1	5.80
Y	2.70
Y1	6.00
Y2	10.90

Tape & reel specification

Tape		Symbol	Dimension (mm)
 SECTION : A-A SECTION : B-B		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.55±0.15
		D1	1.55±0.20
		E	1.75±0.20
		F	7.50±0.20
		W	16.00±0.20
		A0	7.10±0.20
		B0	10.50±0.20
		K0	2.70±0.20
		T	0.30±0.10
		D2	330.0±5.0
		D3	100.0±4.0
13" Reel		W1	20.0±5.0
		D3	100.0±4.0
		W2	25.0±5.0
		I	13.0±2.0
		Quantity: 2500PCS	